CY7C1041CV33

4-Mbit (256 K × 16) Static RAM

Features

- Temperature ranges
  - Commercial: 0 °C to 70°C
- Pin and function compatible with CY7C1041BV33
- High speed
  - t_{AA} = 8 ns
- Low active power
  - 360 mW (max)
- 2.0 V data retention
- Automatic power down when deselected
- TTL-compatible inputs and outputs
- Easy memory expansion with $\overline{CE}$ and $\overline{OE}$ features
- Available in Pb-free 44-pin TSOP II package

Functional Description

The CY7C1041CV33 is a high performance CMOS static RAM organized as 262,144 words by 16 bits.

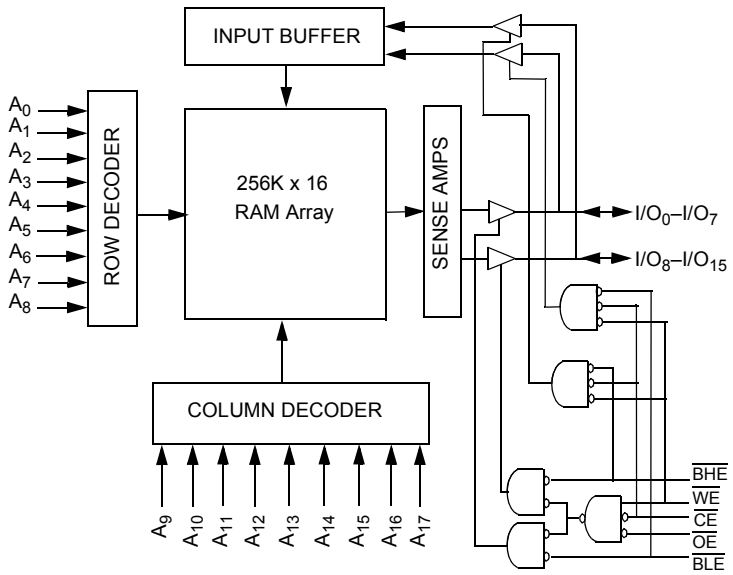
To write to the device, take Chip Enable ($\overline{CE}$) and Write Enable ($\overline{WE}$) inputs LOW. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from I/O pins ($/IO_0$ through I/O_7), is written into the location specified on the address pins (A_0 through A_{17}). If Byte High Enable ($\overline{BHE}$) is LOW, then data from IO pins (I/O_8 through I/O_{15}) is written into the location specified on the address pins (A_0 through A_{17}).

To read from the device, take Chip Enable ($\overline{CE}$) and Output Enable ($\overline{OE}$) LOW while forcing the Write Enable ($\overline{WE}$) HIGH. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from the memory location specified by the address pins appear on I/O_0 to I/O_7. If Byte High Enable ($\overline{BHE}$) is LOW, then data from memory appears on I/O_8 to I/O_{15}. For more information, see the Truth Table on page 10 for a complete description of Read and Write modes.

The input and output pins (I/O_0 through I/O_{15}) are placed in a high impedance state when the device is deselected ($\overline{CE}$ HIGH), the outputs are disabled ($\overline{OE}$ HIGH), the $\overline{BHE}$ and $\overline{BLE}$ are disabled ($\overline{BHE}$, $\overline{BLE}$ HIGH), or during a write operation ($\overline{CE}$ LOW and $\overline{WE}$ LOW).

For best practice recommendations, refer to the Cypress application note AN1064, SRAM System Guidelines.

Logic Block Diagram



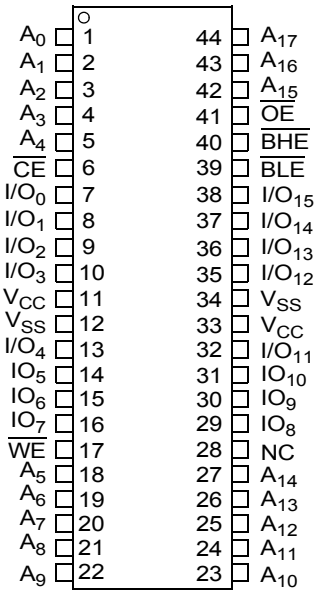
Contents

Selection Guide

Description	-8	Unit
Maximum Access Time	8	ns
Maximum Operating Current	100	mA
Maximum CMOS Standby Current	10	mA

Pin Configuration

Figure 1. 44-pin TSOP II (Top View) [1]



Note
1. NC pins are not connected on the die.

Pin Definitions

Pin Name	TSOP Pin Number	I/O Type	Description
A_0–A_{17}	1–5, 18–27, 42–44	Input	**Address Inputs.** Used to select one of the address locations.
I/O_0–I/O_{15}	7–10,13–16, 29–32, 35–38	Input or Output	**Bidirectional Data IO lines**. Used as input or output lines depending on operation.
NC	28	No Connect	**No Connects**. Not connected to the die.
$\overline{WE}$	17	Input or Control	**Write Enable Input, Active LOW**. When selected LOW, a write is conducted. When deselected HIGH, a read is conducted.
$\overline{CE}$	6	Input or Control	**Chip Enable Input, Active LOW**. When LOW, selects the chip. When HIGH, deselects the chip.
$\overline{BHE}$, $\overline{BLE}$	40, 39	Input or Control	**Byte Write Select Inputs, Active LOW**. $\overline{BHE}$ controls I/O_{15} – I/O_8, $\overline{BLE}$ controls I/O_7 – I/O_0.
$\overline{OE}$	41	Input or Control	**Output Enable, Active LOW**. Controls the direction of the I/O pins. When LOW, the IO pins are allowed to behave as outputs. When deasserted HIGH, the I/O pins are tri-stated and act as input data pins.
V_{SS}	12, 34	Ground	**Ground for the Device**. Connected to ground of the system.
V_{CC}	11, 33	Power Supply	**Power Supply Inputs to the Device.**

Maximum Ratings

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage Temperature ..... –65 °C to +150 °C

Ambient Temperature with Power Applied ..... –55 °C to +125 °C

Supply Voltage on V_{CC} Relative to GND[2] ...–0.5 V to +4.6 V

DC Voltage Applied to Outputs in High Z State[2] ..... –0.5 V to V_{CC} + 0.5 V

DC Input Voltage[2] ..... –0.5 V to V_{CC} + 0.5V

Current into Outputs (LOW)..... 20 mA

Static Discharge Voltage..... > 2001 V (MIL-STD-883, Method 3015)

Latch Up Current ..... > 200 mA

Operating Range

Range	Ambient Temperature (T_A)	V_{CC}
Commercial	0 °C to +70 °C	3.3 V ± 10%

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions	-8		Unit
			Min	Max	
V_{OH}	Output HIGH Voltage	V_{CC} = Min, I_{OH} = –4.0 mA	2.4	–	V
V_{OL}	Output LOW Voltage	V_{CC} = Min, I_{OL} = 8.0 mA	–	0.4	V
V_{IH}	Input HIGH Voltage		2.0	V_{CC} + 0.3	V
V_{IL} [2]	Input LOW Voltage		–0.3	0.8	V
I_{IX}	Input Leakage Current	GND ≤ V_I ≤ V_{CC}	–1	+1	µA
I_{OZ}	Output Leakage Current	GND ≤ V_{OUT} ≤ V_{CC}, Output disabled	–1	+1	µA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max, f = f_{MAX} = 1/t_{RC}	–	100	mA
I_{SB1}	Automatic CE Power Down Current —TTL Inputs	Max V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}	–	40	mA
I_{SB2}	Automatic CE Power Down Current — CMOS Inputs	Max V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3 V, V_{IN} ≥ V_{CC} – 0.3 V, or V_{IN} ≤ 0.3 V, f = 0	–	10	mA

Note
2. V_{IL} (min) = –2.0 V and V_{IH}(max) = V_{CC} + 0.5 V for pulse durations of less than 20 ns.

Capacitance

Tested initially and after any design or process changes that may affect these parameters.

Parameter	Description	Test Conditions	Max	Unit
C_{IN}	Input Capacitance	T_A = 25 °C, f = 1 MHz, V_{CC} = 3.3 V	8	pF
C_{OUT}	Output Capacitance		8	pF

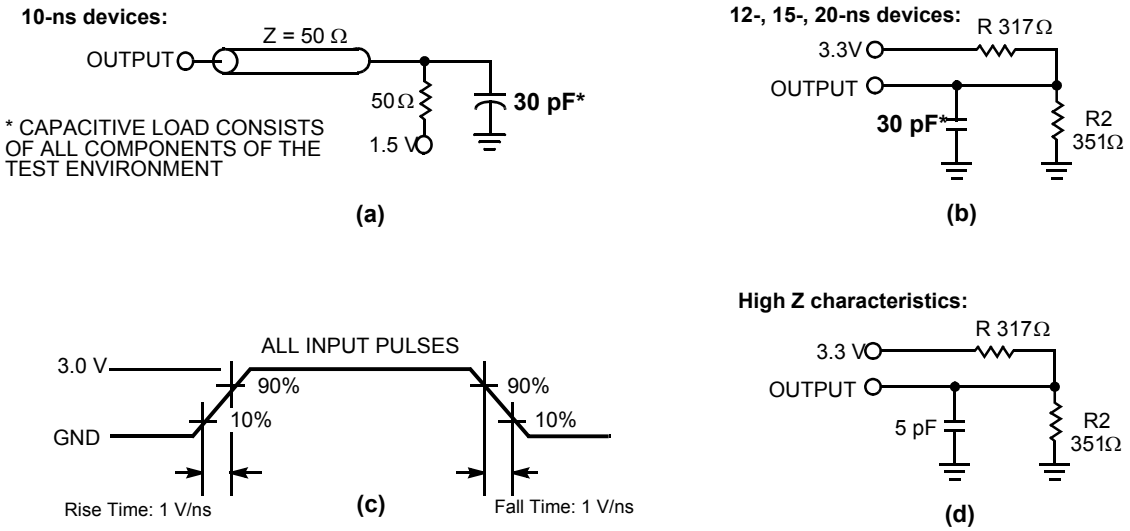
Thermal Resistance

Tested initially and after any design or process changes that may affect these parameters.

Parameter	Description	Test Conditions	TSOP II	Unit
Θ_{JA}	Thermal Resistance (Junction to Ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, per EIA/JESD51	42.96	°C/W
Θ_{JC}	Thermal Resistance (Junction to Case)		10.75	°C/W

AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms [3]



Note

3. AC characteristics (except High Z) for 10-ns parts are tested using the load conditions shown in Figure 2 (a). All other speeds are tested using the Thevenin load shown in Figure 2 (b). High Z characteristics are tested for all speeds using the test load shown in Figure 2 (d).

Switching Characteristics

Over the Operating Range [4]

Parameter	Description	-8		Unit
		Min	Max	
Read Cycle				
t_{power}[5]	V_{CC}(Typical) to the First Access	100	–	µs
t_{RC}	Read Cycle Time	8	–	ns
t_{AA}	Address to Data Valid	–	8	ns
t_{OHA}	Data Hold from Address Change	3	–	ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid	–	8	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid	–	5	ns
t_{LZOE}	$\overline{OE}$ LOW to Low Z[6]	0	–	ns
t_{HZOE}	$\overline{OE}$ HIGH to High Z[6, 7]	–	4	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z[6]	3	–	ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z[6, 7]	–	4	ns
t_{PU}	$\overline{CE}$ LOW to Power Up	0	–	ns
t_{PD}	$\overline{CE}$ HIGH to Power Down	–	8	ns
t_{DBE}	Byte Enable to Data Valid	–	5	ns
t_{LZBE}	Byte Enable to Low Z	0	–	ns
t_{HZBE}	Byte Disable to High Z	–	5	ns
Write Cycle[8, 9]				
t_{WC}	Write Cycle Time	8	–	ns
t_{SCE}	$\overline{CE}$ LOW to Write End	6	–	ns
t_{AW}	Address Setup to Write End	6	–	ns
t_{HA}	Address Hold from Write End	0	–	ns
t_{SA}	Address Setup to Write Start	0	–	ns
t_{PWE}	$\overline{WE}$ Pulse Width	6	–	ns
t_{SD}	Data Setup to Write End	4	–	ns
t_{HD}	Data Hold from Write End	0	–	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low Z[6]	3	–	ns
t_{HZWE}	$\overline{WE}$ LOW to High Z[6, 7]	–	4	ns
t_{BW}	Byte Enable to End of Write	6	–	ns

Notes

4. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5 V, and input pulse levels of 0 to 3.0 V.
5. t_{POWER} gives the minimum amount of time that the power supply is at typical V_{CC} values until the first memory access is performed.
6. At any temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZBE} is less than t_{LZBE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any device.
7. t_{HZOE}, t_{HZCE}, t_{HZBE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (d) of Figure 2 on page 6. Transition is measured ±500 mV from steady state voltage.
8. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW, $\overline{WE}$ LOW, and $\overline{BHE}$/$\overline{BLE}$ LOW. $\overline{CE}$, $\overline{WE}$, and $\overline{BHE}$/$\overline{BLE}$ must be LOW to initiate a write. The transition of these signals terminate the write. The input data setup and hold timing is referenced to the leading edge of the signal that terminates the write.
9. The minimum Write cycle time for Write Cycle No. 3 ($\overline{WE}$ controlled, $\overline{OE}$ LOW) is the sum of t_{HZWE} and t_{SD}.

Switching Waveforms

Figure 3. Read Cycle No. 1 (Address Transition Controlled)[10, 11]

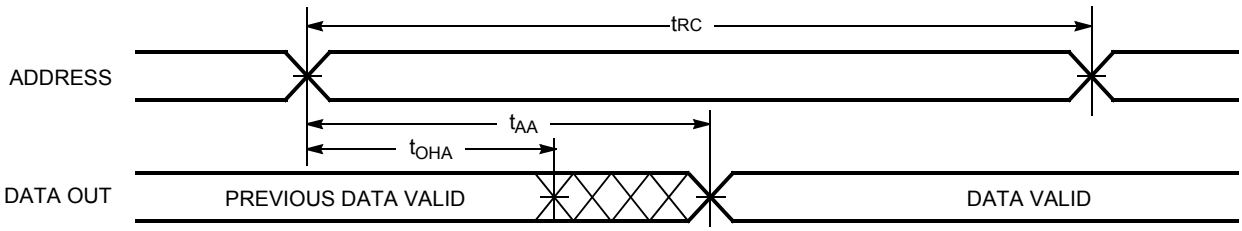
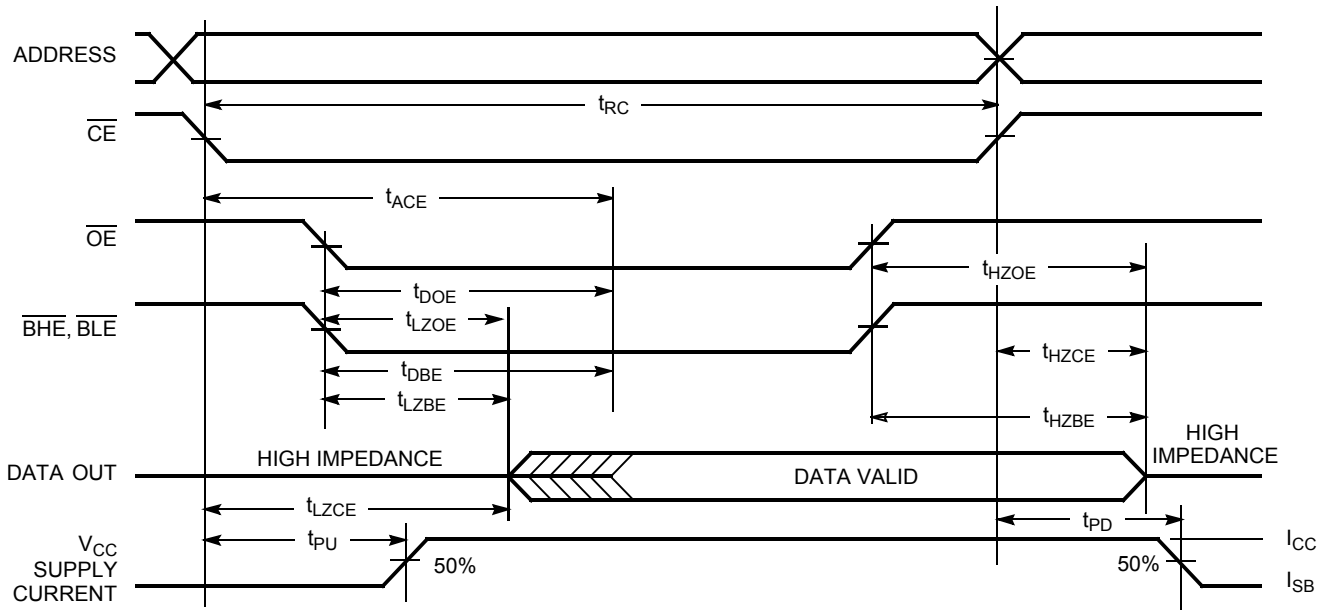


Figure 4. Read Cycle No. 2 ($\overline{OE}$ Controlled)[11, 12]



Notes
10. Device is continuously selected. $\overline{OE}$, $\overline{CE}$, $\overline{BHE}$, and/or $\overline{BLE}$ = V_{IL}.
11. $\overline{WE}$ is HIGH for read cycle.
12. Address valid prior to or coincident with $\overline{CE}$ transition LOW.

Switching Waveforms *(continued)*

Figure 5. Write Cycle No. 1 ($\overline{CE}$ Controlled)[13, 14]

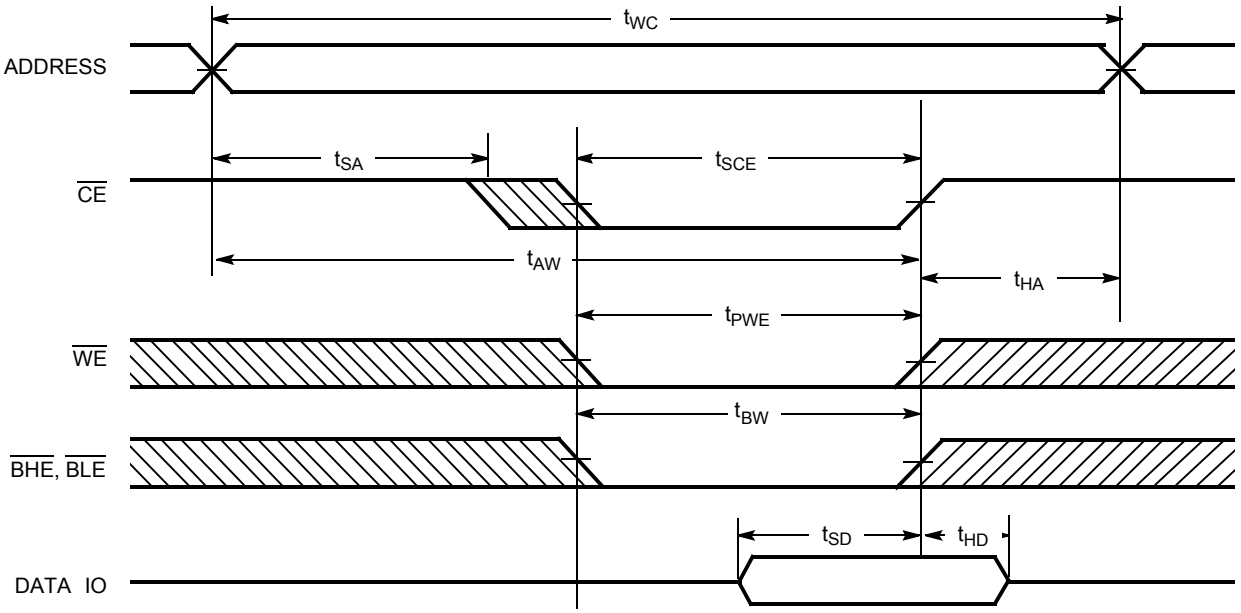
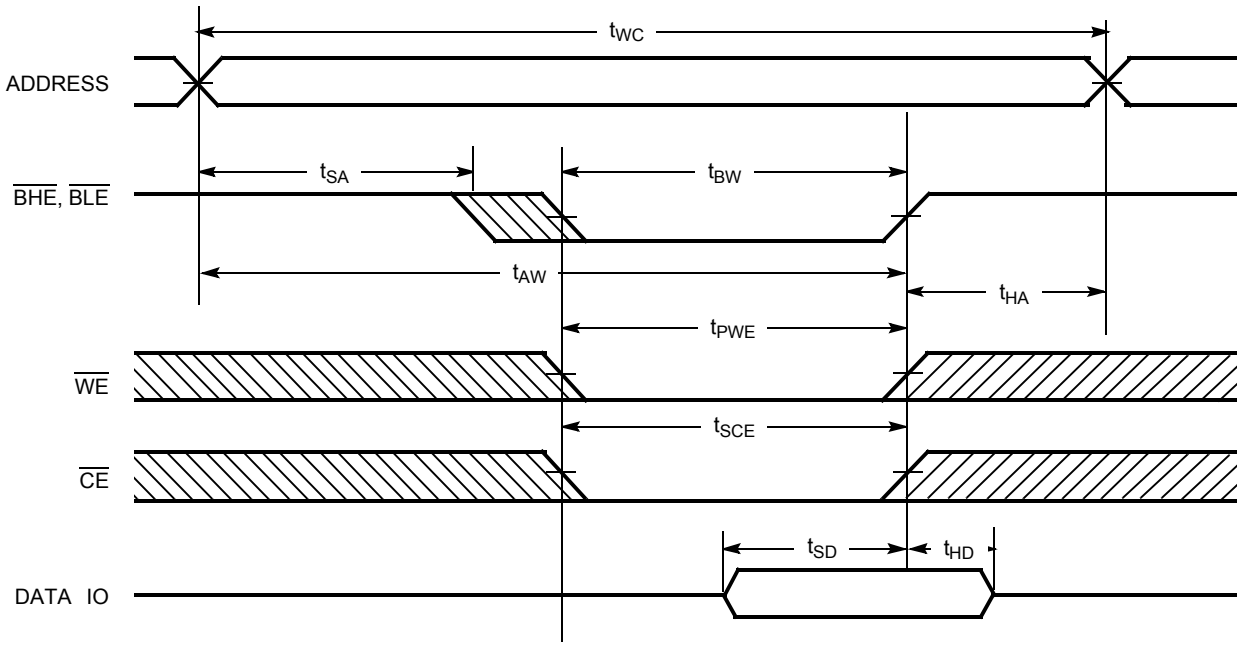


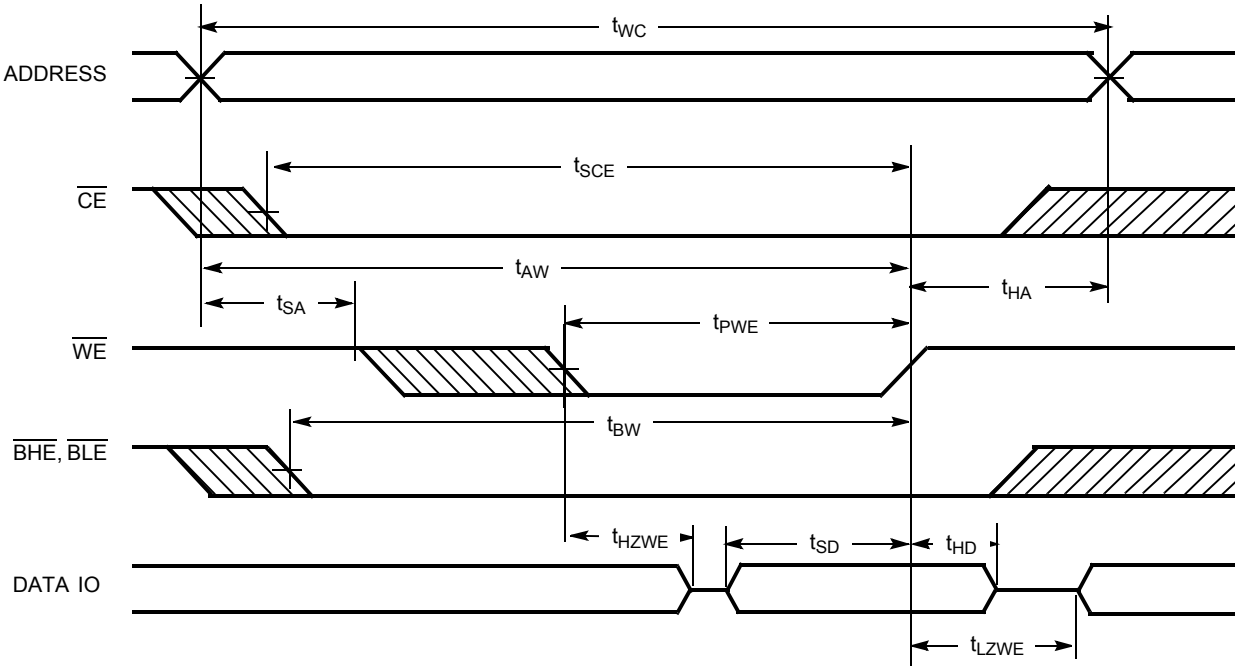
Figure 6. Write Cycle No. 2 ($\overline{BLE}$ or $\overline{BHE}$ Controlled)



Notes
13. Data IO is high impedance if $\overline{OE}$, $\overline{BHE}$, and/or $\overline{BLE}$ = V_{IH}.
14. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ going HIGH, the output remains in a high impedance state.

Switching Waveforms *(continued)*

Figure 7. Write Cycle No. 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)



Truth Table

$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{BLE}$	$\overline{BHE}$	$I/O_0 – I/O_7$	$I/O_8 – I/O_{15}$	Mode	Power
H	X	X	X	X	High Z	High Z	Power Down	Standby (I_{SB})
L	L	H	L	L	Data Out	Data Out	Read – All Bits	Active (I_{CC})
			L	H	Data Out	High Z	Read – Lower Bits Only	Active (I_{CC})
			H	L	High Z	Data Out	Read – Upper Bits Only	Active (I_{CC})
L	X	L	L	L	Data In	Data In	Write – All Bits	Active (I_{CC})
			L	H	Data In	High Z	Write – Lower Bits Only	Active (I_{CC})
			H	L	High Z	Data In	Write – Upper Bits Only	Active (I_{CC})
L	H	H	X	X	High Z	High Z	Selected, Outputs Disabled	Active (I_{CC})
L	X	X	H	H	High Z	High Z	Selected, Outputs Disabled	Active (I_{CC})

Ordering Information

Cypress offers other versions of this type of product in many different configurations and features. The below table contains only the list of parts that are currently available.For a complete listing of all options, visit the Cypress website at www.cypress.com and refer to the product summary page at http://www.cypress.com/products or contact your local sales representative.

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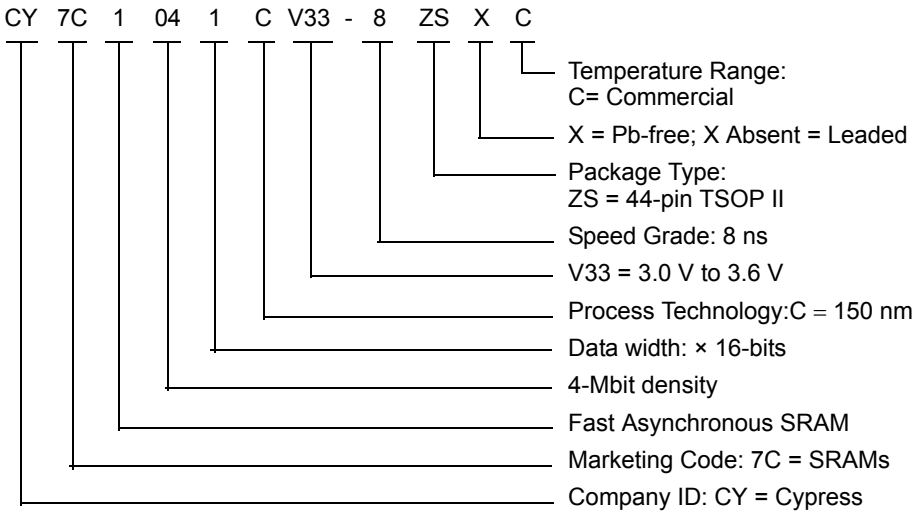
Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
8	CY7C1041CV33-8ZSXC	51-85087	44-pin Thin Small Outline Package Type II (Pb-free)	Commercial

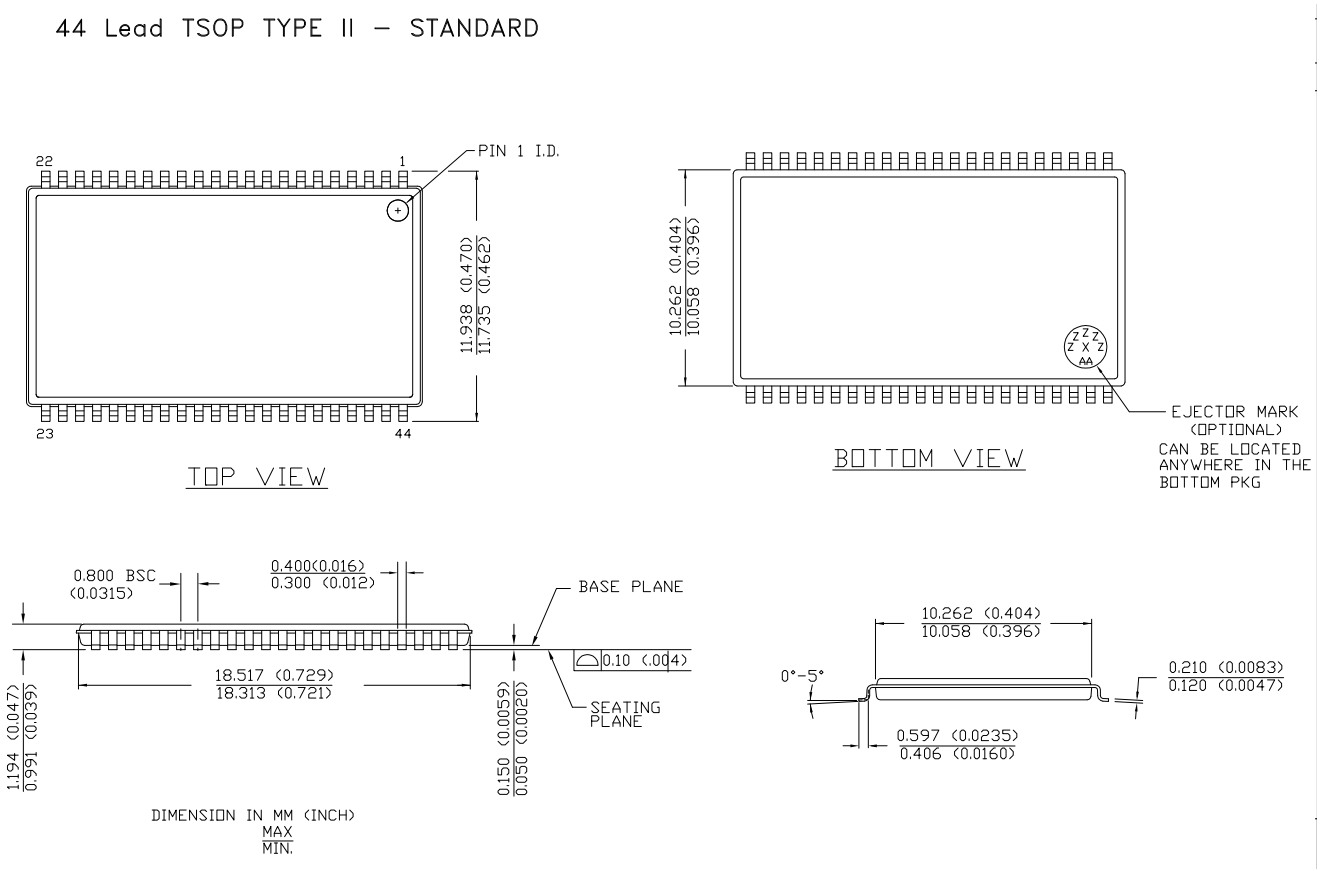
Please contact your local Cypress sales representative for availability of these parts

Ordering Code Definitions



Package Diagram

Figure 8. 44-pin Thin Small Outline Package Type II, 51-85087



Acronyms

Acronym	Description
$\overline{CE}$	Chip Enable
CMOS	complementary metal oxide semiconductor
FBGA	fine-pitch ball grid array
I/O	input/output
$\overline{OE}$	Output Enable
SOJ	Small Outline J-lead
SRAM	static random access memory
TSOP	thin small outline package
TTL	transistor-transistor logic
$\overline{WE}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
Ω	ohms
ns	nano seconds
V	Volts
µs	micro seconds
µA	micro Amperes
mA	milli Amperes
mm	milli meter
ms	milli seconds
MHz	Mega Hertz
pF	pico Farad
%	percent
mW	milli Watts
W	Watts
°C	degree Celcius

Document History Page

Document Title: CY7C1041CV33, 4-Mbit (256 K × 16) Static RAM Document Number: 38-05134				
REV.	**ECN NO.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	109513	12/13/01	HGK	New Data Sheet
*A	112440	12/20/01	BSS	Updated 51-85106 from revision *A to *C
*B	112859	03/25/02	DFP	Added CY7C1042CV33 in BGA package Removed 1042 BGA option pin ACC Final Data Sheet
*C	116477	09/16/02	CEA	Add applications foot note to data sheet
*D	119797	10/21/02	DFP	Added 20-ns speed bin
*E	262949	See ECN	RKF	1) Added Lead (Pb)-Free parts in the Ordering info (Page #9) 2) Added Automotive Specs to Datasheet
*F	361795	See ECN	SYT	Added Pb-Free offerings in the Ordering Information
*G	435387	See ECN	NXR	Removed -8 Speed bin from Product offering. Corrected typo in description for BHE/BLE in pin definitions table on Page# 3 corrected their Pin name from OE2 to OE. Included the Maximum Ratings for Static Discharge Voltage and Latch up Current. Changed the description of I_{IX} current from Input Load Current to Input Leakage Current Added note# 4 on page# 4 Updated the Ordering Information table
*H	499153	See ECN	NXR	Added Automotive-A Operating Range Changed t_{power} value from 1 µs to 100 µs Updated Ordering Information table
*I	2104110	See ECN	VKN/AESA	Added Automotive-E specs for 12 ns speed Updated Ordering Information table
*J	2897141	03/22/10	AJU/VIVG	Removed inactive parts. Updated package diagrams.
*K	3072834	11/12/2010	PRAS	Removed inactive parts. Added Ordering Code Definitions on page 11.
*L	3186840	03/03/2011	PRAS	Updated Features. Updated Selection Guide (Added -8 ns speed grade devices and removed -10 ns, -12 ns, -15 ns and -20 ns speed grade devices). Removed Figure “48-Ball FBGA Pinout (Top View)” and renamed Figure “44-Pin SOJ/TSOP II (Top View)” as “44-pin TSOP II (Top View)” in Pin Configuration. Updated Pin Definitions (Deleted the column “BGA Pin Number” and renamed the column “SOJ, TSOP Pin Number” as “TSOP Pin Number”. Updated Operating Range Updated Electrical Characteristics (Added -8 ns speed grade devices and removed -10 ns, -12 ns, -15 ns and -20 ns speed grade devices). Updated Thermal Resistance (Deleted the columns SOJ and FBGA). Updated Switching Characteristics (Added -8 ns speed grade devices and removed -10 ns, -12 ns, -15 ns and -20 ns speed grade devices). Updated Ordering Information (Added new speed bin (-8 ns speed grade devices) and removed -10 ns, -12 ns, -15 ns and -20 ns speed grade devices). Added Acronyms and Units of Measure. Dislodged Automotive information to new datasheet (001-67307) Removed SOJ and FBGA package related information in all instances in the document. Updated in new template.

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